

SN54LV367A, SN74LV367A HEX BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

SCLS398G – APRIL 1998 – REVISED APRIL 2005

- 2-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 7 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce)
<0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot)
>2.3 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Support Mixed-Mode Voltage Operation on All Ports
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

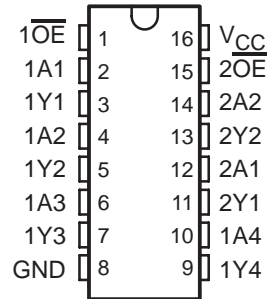
description/ordering information

The 'LV367A devices are hex buffers and line drivers designed for 2-V to 5.5-V V_{CC} operation. These devices are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

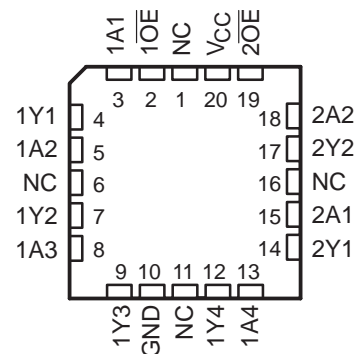
The 'LV367A devices are organized as dual 4-line and 2-line buffers/drivers with active-low output-enable ($\overline{1OE}$ and $\overline{2OE}$) inputs. When \overline{OE} is low, the device passes noninverted data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

SN54LV367A . . . J OR W PACKAGE
SN74LV367A . . . D, DB, DGV, NS, OR PW PACKAGE
(TOP VIEW)



SN54LV367A . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

ORDERING INFORMATION

| T_A | PACKAGE† | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|-------------|--------------|-----------------------|------------------|
| –40°C to 85°C | SOIC – D | Tube of 40 | SN74LV367AD | LV367A |
| | | Reel of 2500 | SN74LV367ADR | |
| | SOP – NS | Reel of 2000 | SN74LV367ANSR | 74LV367A |
| | SSOP – DB | Reel of 2000 | SN74LV367ADBR | LV36A |
| | TSSOP – PW | Reel of 2000 | SN74LV367APWR | LV367A |
| | | Reel of 250 | SN74LV367APWT | |
| –55°C to 125°C | TVSOP – DGV | Reel of 2000 | SN74LV367ADGVR | LV367A |
| | CDIP – J | Tube of 25 | SNJ54LV367AJ | SNJ54LV367AJ |
| | CFP – W | Tube of 150 | SNJ54LV367AW | SNJ54LV367AW |
| | LCCC – FK | Tube of 55 | SNJ54LV367AFK | SNJ54LV367AFK |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

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 **TEXAS
INSTRUMENTS**

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SN54LV367A, SN74LV367A HEX BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

SCLS398G – APRIL 1998 – REVISED APRIL 2005

FUNCTION TABLE
(each buffer/driver)

| INPUTS | | OUTPUT |
|-----------------|---|--------|
| \overline{OE} | A | Y |
| L | H | H |
| L | L | L |
| H | X | Z |

logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, J, NS, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| | |
|--|----------------------------|
| Supply voltage range, V_{CC} | -0.5 V to 7 V |
| Input voltage range, V_I (see Note 1) | -0.5 V to 7 V |
| Voltage range applied to any output in the high-impedance or power-off state, V_O (see Note 1) | -0.5 V to 7 V |
| Output voltage range applied in the high or low state, V_O (see Notes 1 and 2) | -0.5 V to $V_{CC} + 0.5$ V |
| Input clamp current, I_{IK} ($V_I < 0$) | -20 mA |
| Output clamp current, I_{OK} ($V_O < 0$) | -50 mA |
| Continuous output current, I_O ($V_O = 0$ to V_{CC}) | ± 35 mA |
| Continuous current through V_{CC} or GND | ± 70 mA |
| Package thermal impedance, θ_{JA} (see Note 3): | |
| D package | 73°C/W |
| DB package | 82°C/W |
| DGV package | 120°C/W |
| NS package | 64°C/W |
| PW package | 108°C/W |
| Storage temperature range, T_{stg} | -65°C to 150°C |

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 2. This value is limited to 5.5 V maximum.
 3. The package thermal impedance is calculated in accordance with JESD 51-7.

SN54LV367A, SN74LV367A HEX BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

SCLS398G – APRIL 1998 – REVISED APRIL 2005

recommended operating conditions (see Note 4)

| | | SN54LV367A | | SN74LV367A | | UNIT | |
|-----------------|------------------------------------|----------------------------------|-----------------------|-----------------------|-----|-----------------|---|
| | | MIN | MAX | MIN | MAX | | |
| V _{CC} | Supply voltage | 2 | 5.5 | 2 | 5.5 | V | |
| V _{IH} | High-level input voltage | V _{CC} = 2 V | 1.5 | 1.5 | | V | |
| | | V _{CC} = 2.3 V to 2.7 V | V _{CC} × 0.7 | V _{CC} × 0.7 | | | |
| | | V _{CC} = 3 V to 3.6 V | V _{CC} × 0.7 | V _{CC} × 0.7 | | | |
| | | V _{CC} = 4.5 V to 5.5 V | V _{CC} × 0.7 | V _{CC} × 0.7 | | | |
| V _{IL} | Low-level input voltage | V _{CC} = 2 V | 0.5 | 0.5 | | V | |
| | | V _{CC} = 2.3 V to 2.7 V | V _{CC} × 0.3 | V _{CC} × 0.3 | | | |
| | | V _{CC} = 3 V to 3.6 V | V _{CC} × 0.3 | V _{CC} × 0.3 | | | |
| | | V _{CC} = 4.5 V to 5.5 V | V _{CC} × 0.3 | V _{CC} × 0.3 | | | |
| V _I | Input voltage | 0 | 5.5 | 0 | 5.5 | V | |
| V _O | Output voltage | High or low state | 0 | V _{CC} | 0 | V _{CC} | V |
| | | 3-state | 0 | 5.5 | 0 | 5.5 | |
| I _{OH} | High-level output current | V _{CC} = 2 V | | -50 | -50 | μA | |
| | | V _{CC} = 2.3 V to 2.7 V | | -2 | -2 | mA | |
| | | V _{CC} = 3 V to 3.6 V | | -8 | -8 | | |
| | | V _{CC} = 4.5 V to 5.5 V | | -16 | -16 | | |
| I _{OL} | Low-level output current | V _{CC} = 2 V | | 50 | 50 | μA | |
| | | V _{CC} = 2.3 V to 2.7 V | | 2 | 2 | mA | |
| | | V _{CC} = 3 V to 3.6 V | | 8 | 8 | | |
| | | V _{CC} = 4.5 V to 5.5 V | | 16 | 16 | | |
| Δt/Δv | Input transition rise or fall rate | V _{CC} = 2.3 V to 2.7 V | | 200 | 200 | ns/V | |
| | | V _{CC} = 3 V to 3.6 V | | 100 | 100 | | |
| | | V _{CC} = 4.5 V to 5.5 V | | 20 | 20 | | |
| T _A | Operating free-air temperature | -55 | 125 | -40 | 85 | °C | |

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN54LV367A, SN74LV367A HEX BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

SCLS398G – APRIL 1998 – REVISED APRIL 2005

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CC} | SN54LV367A | | | SN74LV367A | | | UNIT |
|------------------|---|-----------------|----------------------|-----|-----|----------------------|-----|-----|------|
| | | | MIN | TYP | MAX | MIN | TYP | MAX | |
| V _{OH} | I _{OH} = -50 μA | 2 V to 5.5 V | V _{CC} -0.1 | | | V _{CC} -0.1 | | | V |
| | I _{OH} = -2 mA | 2.3 V | 2 | | | 2 | | | |
| | I _{OH} = -8 mA | 3 V | 2.48 | | | 2.48 | | | |
| | I _{OH} = -16 mA | 4.5 V | 3.8 | | | 3.8 | | | |
| V _{OL} | I _{OL} = 50 μA | 2 V to 5.5 V | | | | 0.1 | | | V |
| | I _{OL} = 2 mA | 2.3 V | | | | 0.4 | | | |
| | I _{OL} = 8 mA | 3 V | | | | 0.44 | | | |
| | I _{OL} = 16 mA | 4.5 V | | | | 0.55 | | | |
| I _I | V _I = 5.5 V or GND | 0 to 5.5 V | | | | ±1 | | | μA |
| I _{OZ} | V _O = V _{CC} or GND | 5.5 V | | | | ±5 | | | μA |
| I _{CC} | V _I = V _{CC} or GND, I _O = 0 | 5.5 V | | | | 20 | | | μA |
| I _{off} | V _I or V _O = 0 to 5.5 V | 0 | | | | 5 | | | μA |
| C _i | V _I = V _{CC} or GND | 3.3 V | 3 | | | 3 | | | pF |
| C _o | V _I = V _{CC} or GND | 3.3 V | 5.2 | | | 5.2 | | | pF |

switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V ± 0.2 V (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | LOAD CAPACITANCE | T _A = 25°C | | | SN54LV367A | | SN74LV367A | | UNIT |
|--------------------|------------------------|-------------|------------------------|-----------------------|-------|-----|------------|-----|------------|-----|------|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| t _{pd} | A | Y | C _L = 15 pF | 6.4* | 12.7* | | 1* | 16* | 1 | 16 | ns |
| t _{en} | $\overline{\text{OE}}$ | Y | | 6.9* | 14.9* | | 1* | 20* | 1 | 20 | |
| t _{dis} | $\overline{\text{OE}}$ | Y | | 6.4* | 14.9* | | 1* | 20* | 1 | 20 | |
| t _{pd} | A | Y | C _L = 50 pF | 8.6 | 17.5 | | 1 | 21 | 1 | 21 | ns |
| t _{en} | $\overline{\text{OE}}$ | Y | | 9.4 | 19.7 | | 1 | 25 | 1 | 25 | |
| t _{dis} | $\overline{\text{OE}}$ | Y | | 10.1 | 19.7 | | 1 | 25 | 1 | 25 | |
| t _{sk(o)} | | | | | | | 2 | | | 2 | |

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | LOAD CAPACITANCE | T _A = 25°C | | | SN54LV367A | | SN74LV367A | | UNIT |
|--------------------|------------------------|-------------|------------------------|-----------------------|-------|-----|------------|-------|------------|------|------|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| t _{pd} | A | Y | C _L = 15 pF | 4.7* | 8.3* | | 1* | 10* | 1 | 10 | ns |
| t _{en} | $\overline{\text{OE}}$ | Y | | 5.1* | 10.5* | | 1* | 12.5* | 1 | 12.5 | |
| t _{dis} | $\overline{\text{OE}}$ | Y | | 4.9* | 10.5* | | 1* | 12.5* | 1 | 12.5 | |
| t _{pd} | A | Y | C _L = 50 pF | 6.2 | 11.8 | | 1 | 13.5 | 1 | 13.5 | ns |
| t _{en} | $\overline{\text{OE}}$ | Y | | 6.8 | 14 | | 1 | 16 | 1 | 16 | |
| t _{dis} | $\overline{\text{OE}}$ | Y | | 7.3 | 13.6 | | 1 | 15.5 | 1 | 15.5 | |
| t _{sk(o)} | | | | | | | 1.5 | | | 1.5 | |

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



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SCLS398G – APRIL 1998 – REVISED APRIL 2005

switching characteristics over recommended operating free-air temperature range, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | LOAD CAPACITANCE | $T_A = 25^\circ\text{C}$ | | | SN54LV367A | | SN74LV367A | | UNIT |
|-------------|-----------------|-------------|----------------------|--------------------------|------|-----|------------|-----|------------|-----|------|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| t_{pd} | A | Y | $C_L = 15\text{ pF}$ | 3.6* | 5.9* | 1* | 7* | 1 | 7 | ns | |
| t_{en} | \overline{OE} | Y | | 3.8* | 7.2* | 1* | 8.5* | 1 | 8.5 | | |
| t_{dis} | \overline{OE} | Y | | 2.6* | 7.2* | 1* | 8.5* | 0 | 8.5 | | |
| t_{pd} | A | Y | $C_L = 50\text{ pF}$ | 4.5 | 7.9 | 1 | 9 | 1 | 9 | ns | |
| t_{en} | \overline{OE} | Y | | 4.9 | 9.2 | 1 | 10.5 | 1 | 10.5 | | |
| t_{dis} | \overline{OE} | Y | | 4.5 | 9.2 | 1 | 10.5 | 0 | 10.5 | | |
| $t_{sk(o)}$ | | | | | | 1 | | | 1 | | |

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, $V_{CC} = 3.3\text{ V}$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$ (see Note 5)

| PARAMETER | | SN74LV367A | | | UNIT |
|-------------|--|------------|------|-----|------|
| | | MIN | TYP | MAX | |
| $V_{OL(P)}$ | Quiet output, maximum dynamic V_{OL} | 0.5 | 0.8 | | V |
| $V_{OL(V)}$ | Quiet output, minimum dynamic V_{OL} | -0.2 | -0.8 | | V |
| $V_{OH(V)}$ | Quiet output, minimum dynamic V_{OH} | 3 | | | V |
| $V_{IH(D)}$ | High-level dynamic input voltage | 2.31 | | | V |
| $V_{IL(D)}$ | Low-level dynamic input voltage | | 0.99 | | V |

NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics, $T_A = 25^\circ\text{C}$

| PARAMETER | | TEST CONDITIONS | V_{CC} | TYP | UNIT |
|-----------|-------------------------------|--|----------|------|------|
| C_{pd} | Power dissipation capacitance | $C_L = 50\text{ pF}$, $f = 10\text{ MHz}$ | 3.3 V | 14.9 | pF |
| | | | 5 V | 17.4 | |

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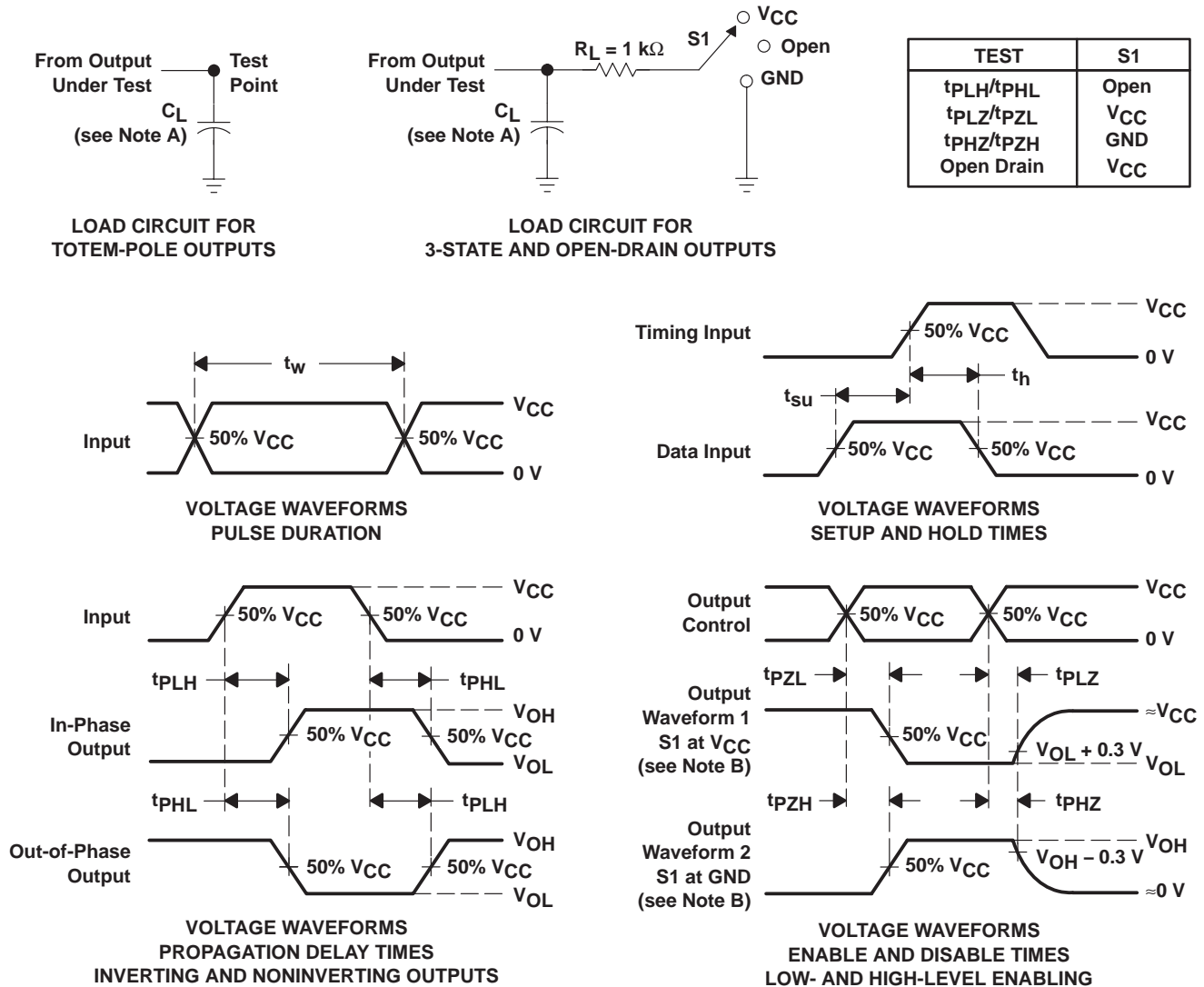


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SCLS398G – APRIL 1998 – REVISED APRIL 2005

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR $\leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
 - D. The outputs are measured one at a time, with one input transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PHL} and t_{PLH} are the same as t_{pd} .
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|-------------------------|
| SN74LV367AD | ACTIVE | SOIC | D | 16 | 40 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | LV367A | Samples |
| SN74LV367ADE4 | ACTIVE | SOIC | D | 16 | 40 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | LV367A | Samples |
| SN74LV367ADGVR | ACTIVE | TVSOP | DGV | 16 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | LV367A | Samples |
| SN74LV367ADR | ACTIVE | SOIC | D | 16 | 2500 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | LV367A | Samples |
| SN74LV367ANSR | ACTIVE | SO | NS | 16 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | 74LV367A | Samples |
| SN74LV367APWR | ACTIVE | TSSOP | PW | 16 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | LV367A | Samples |
| SN74LV367APWRG4 | ACTIVE | TSSOP | PW | 16 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | LV367A | Samples |
| SN74LV367APWT | ACTIVE | TSSOP | PW | 16 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | LV367A | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74LV367ADGVR | TVSOP | DGV | 16 | 2000 | 330.0 | 12.4 | 6.8 | 4.0 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74LV367ADR | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74LV367ANSR | SO | NS | 16 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74LV367APWR | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74LV367APWT | TSSOP | PW | 16 | 250 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |

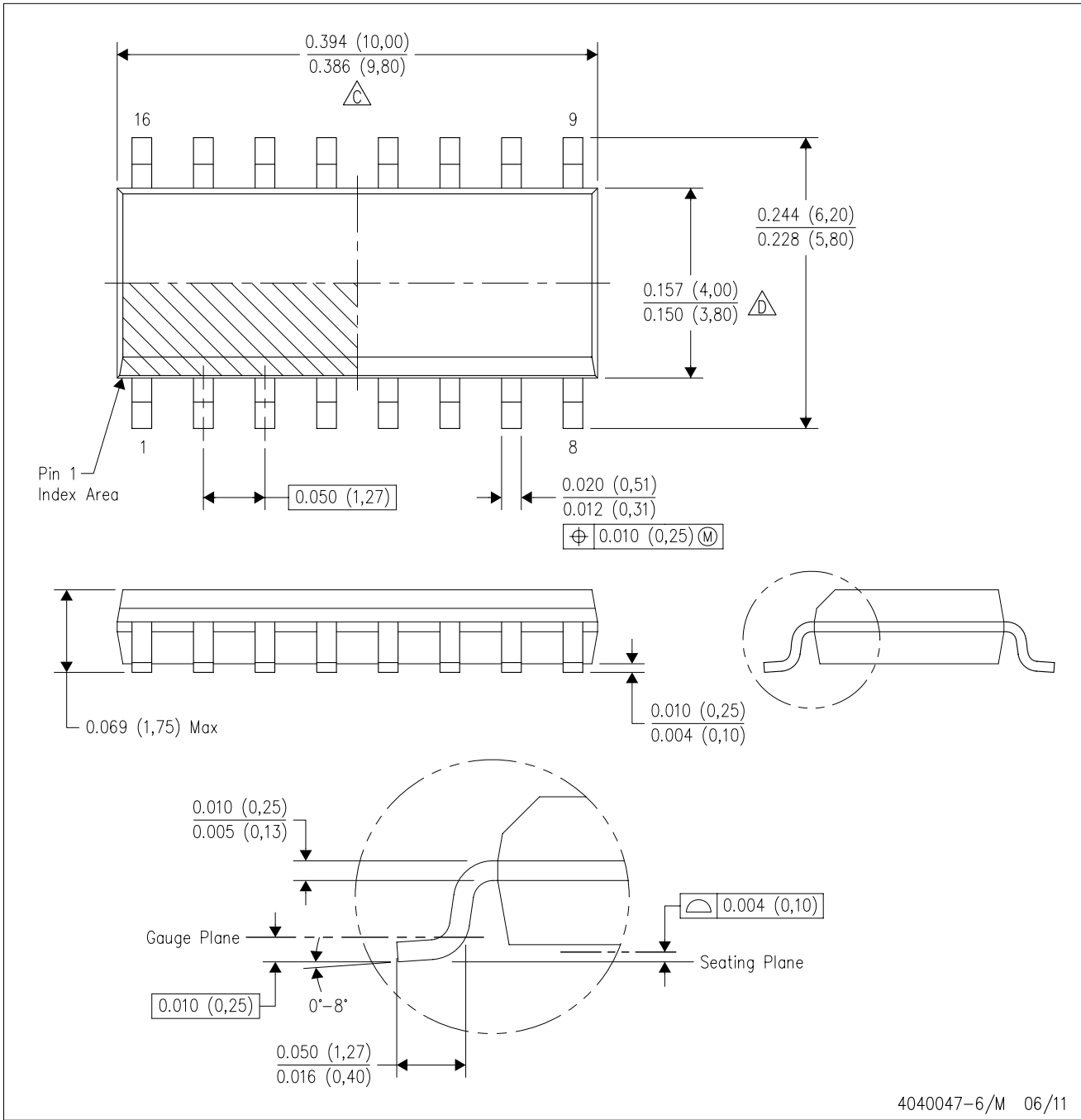
TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74LV367ADGVR | TVSOP | DGV | 16 | 2000 | 853.0 | 449.0 | 35.0 |
| SN74LV367ADR | SOIC | D | 16 | 2500 | 333.2 | 345.9 | 28.6 |
| SN74LV367ANSR | SO | NS | 16 | 2000 | 367.0 | 367.0 | 38.0 |
| SN74LV367APWR | TSSOP | PW | 16 | 2000 | 853.0 | 449.0 | 35.0 |
| SN74LV367APWT | TSSOP | PW | 16 | 250 | 853.0 | 449.0 | 35.0 |

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040047-6/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



4220204/A 02/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220204/A 02/2017

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

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